

## RELIABILITY DATA

### LT1460 / LT1790 / LT6653 / LT6660 / LT6703

**6/8/2012**

**• OPERATING LIFE TEST**

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS <sup>(1)</sup> AT +125°C	NUMBER OF FAILURES <sup>(2)</sup>
PLASTIC DIP	438	9640	9914	464.31	0
SOIC/SOT/MSOP	897	9633	0721	824.03	0
	1,335			1,288.34	0

**• HIGHLY ACCELERATED STRESS TEST AT +131°C/85%RH**

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS <sup>(4)</sup> AT +85°C	NUMBER OF FAILURES
SOIC/SOT/MSOP	522	9644	0935	1,289.72	0
	522			1,289.72	0

**• PRESSURE COOKER TEST AT 15 PSIG, +121°C**

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS	NUMBER OF FAILURES
PLASTIC DIP	1,210	9641	0738	63.39	0
SOIC/SOT/MSOP	37,585	9631	1121	2,444.76	0
TO-92	1,975	9723	1050	262.12	0
QFN/DFN	880	0619	1045	108.48	0
	41,650			2,878.75	0

**• TEMP CYCLE FROM -65°C to +150°C**

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
PLASTIC DIP	458	9714	0738	188.00	0
SOIC/SOT/MSOP	24,964	9631	1121	6,941.32	0
TO-92	1,634	9740	1108	937.60	0
QFN/DFN	744	0619	1045	74.40	0
	27,800			8,141.32	0

**• THERMAL SHOCK FROM -65°C to +150°C**

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
PLASTIC DIP	273	9735	0738	183.00	0
SOIC/SOT/MSOP	23,264	9536	1121	5,271.14	0
TO-92	1,865	9735	1050	1,036.70	0
QFN/DFN	739	0619	1045	73.90	0
	26,141			6,564.74	0

(1) Assumes Activation Energy = 1.0 Electron Volts

(2) Failure Rate Equivalent to +55°C, 60% Confidence Level = 1.43 FITS

(3) Mean Time Between Failures in Years = 79,774

(4) Assumes 20X Acceleration from 85°C to +131°C

Note: 1 FIT = 1 Failure in One Billion Hours.